

Application No. 09/524,227
 Docket No. 13DV-13004
 Amendment dated February 21, 2005
 Reply to Office Action of October 22, 2004

REMARKS

In the Office Action, filed in response to Applicant's RCE filed August 4, 2004, the Examiner reviewed claims 1-20 of the above-identified US Patent Application, with the result that all of the claims were again rejected under 35 USC §103. In response, Applicant has amended the claims as set forth above. More particularly, independent claim 1 has been amended to incorporate the limitations of its dependent claim 9, which in turn has been amended to require that recrystallization of the surface region of the aluminide bond coat occurs during deposition of the thermal barrier coating on the surface of the aluminide bond coat. Support for the latter amendment can be found in the second to last paragraph of Applicant's specification.

Applicant believes that the above amendments do not present new matter. Favorable reconsideration and allowance of claims 1-20 are respectfully requested in view of the above amendments and the following remarks.

Independent claims 1, 11, and 20 and their dependent claims 2-10 and 12-19 were again rejected under 35 USC §103(a) as being unpatentable over Applicant's admitted prior art (AAPA) in view of Japanese patent JP 01-180959 A to Nakamura et al. (Nakamura), either alone or in further view of one

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or more of U.S. Patent Nos. 4,514,469 to Loersch et al. (Loersch), 4,512,817 to Duhl et al. (Duhl), 6,042,898 to Burns et al. (Burns), and 6,365,236 to Maloney. The combination of the AAPA and Nakamura is essential to each of the §103 rejections. As in previous Office Actions, the rejections were generally set forth as follows: the Examiner cited the AAPA as disclosing a thermal barrier coating system (20) comprising an aluminide bond coat (24) characterized by substantially columnar grains (32) and grain boundaries (34) exposed at the bond coat surface, acknowledged that the AAPA does not teach recrystallizing at least a surface region of the bond coat (24) during or prior to

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